

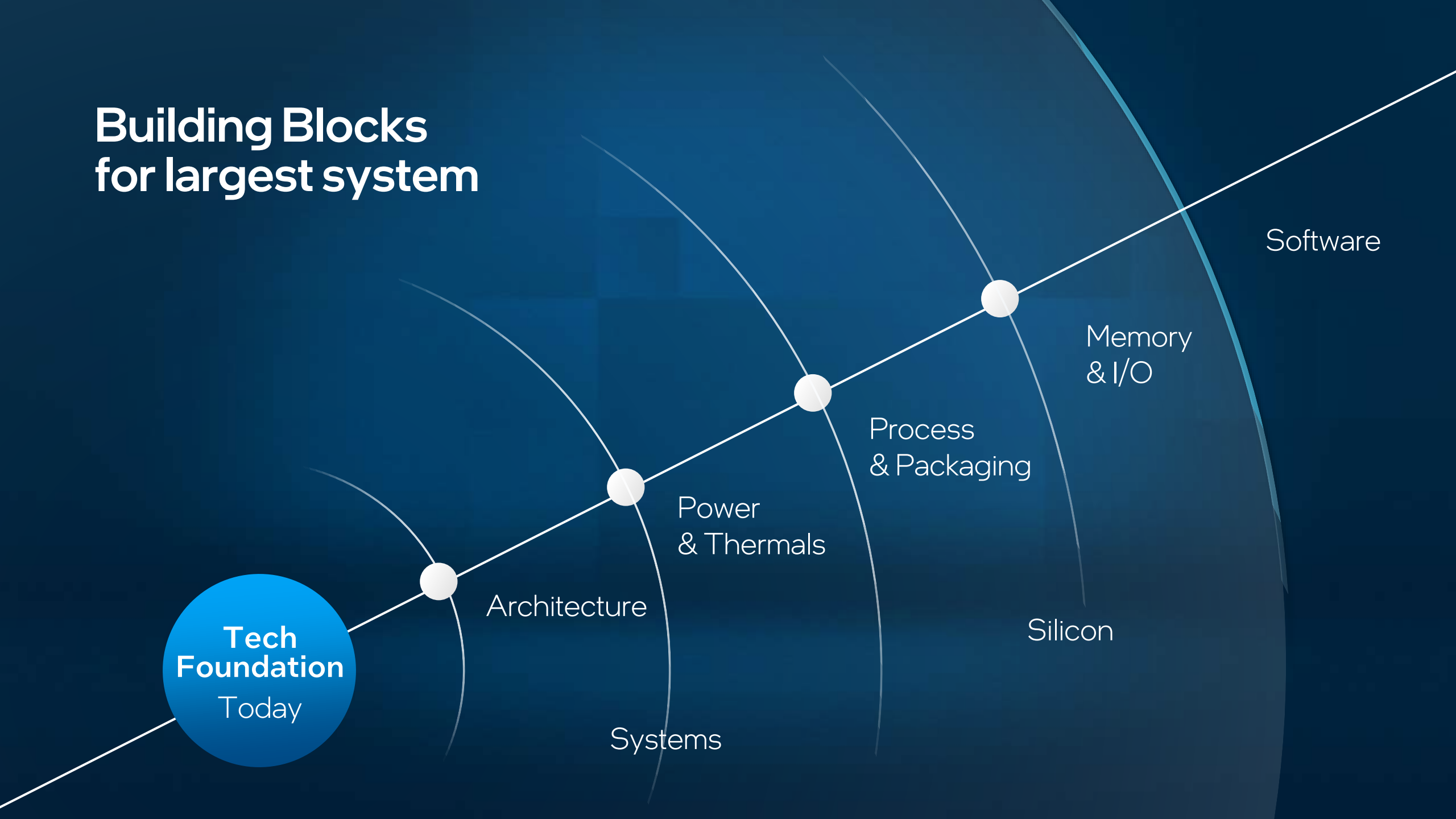
Modularity and disaggregation

Jean Laurent PHILIPPE
EMEA CTO

intel.

Forum
TERATEC 23

Building Blocks for largest system





Silicon

Systems

Software



Silicon

Systems

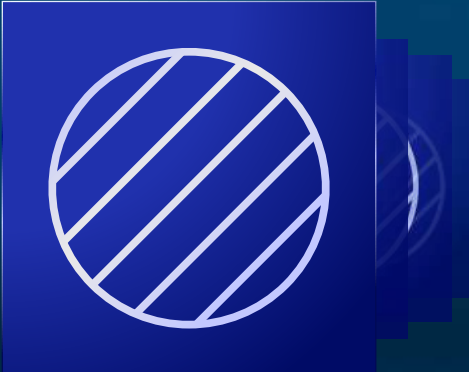
Software

Workload Heterogeneity

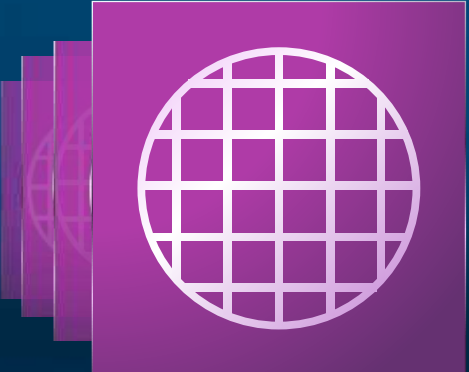
Scalar



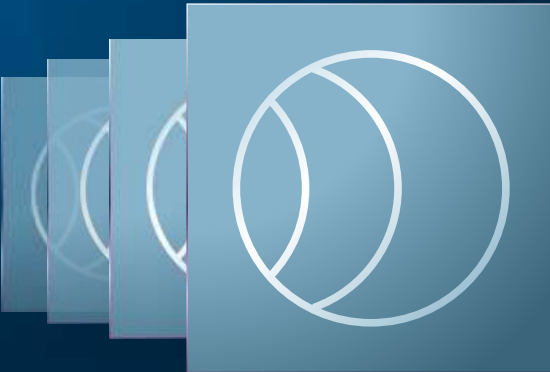
Vector



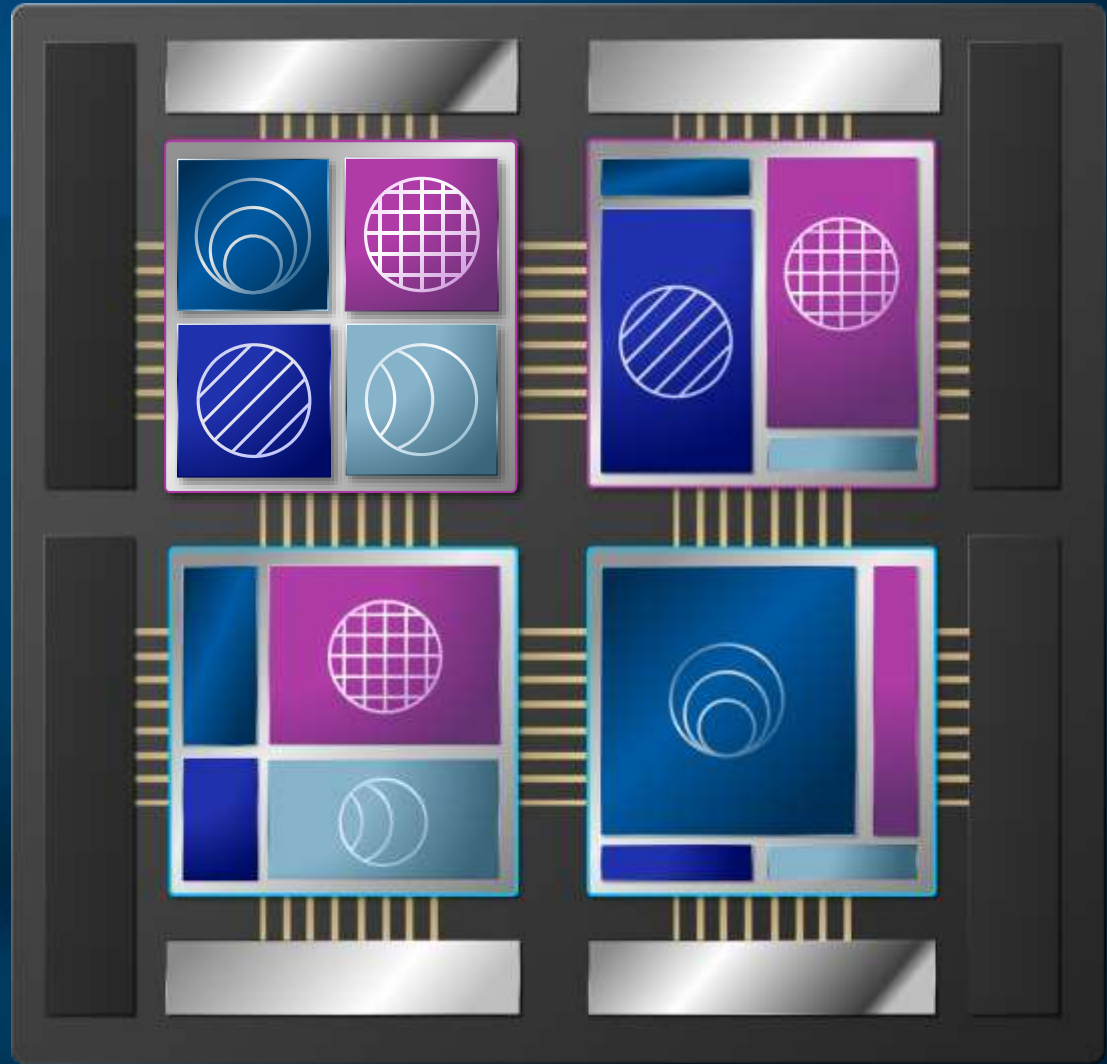
Matrix

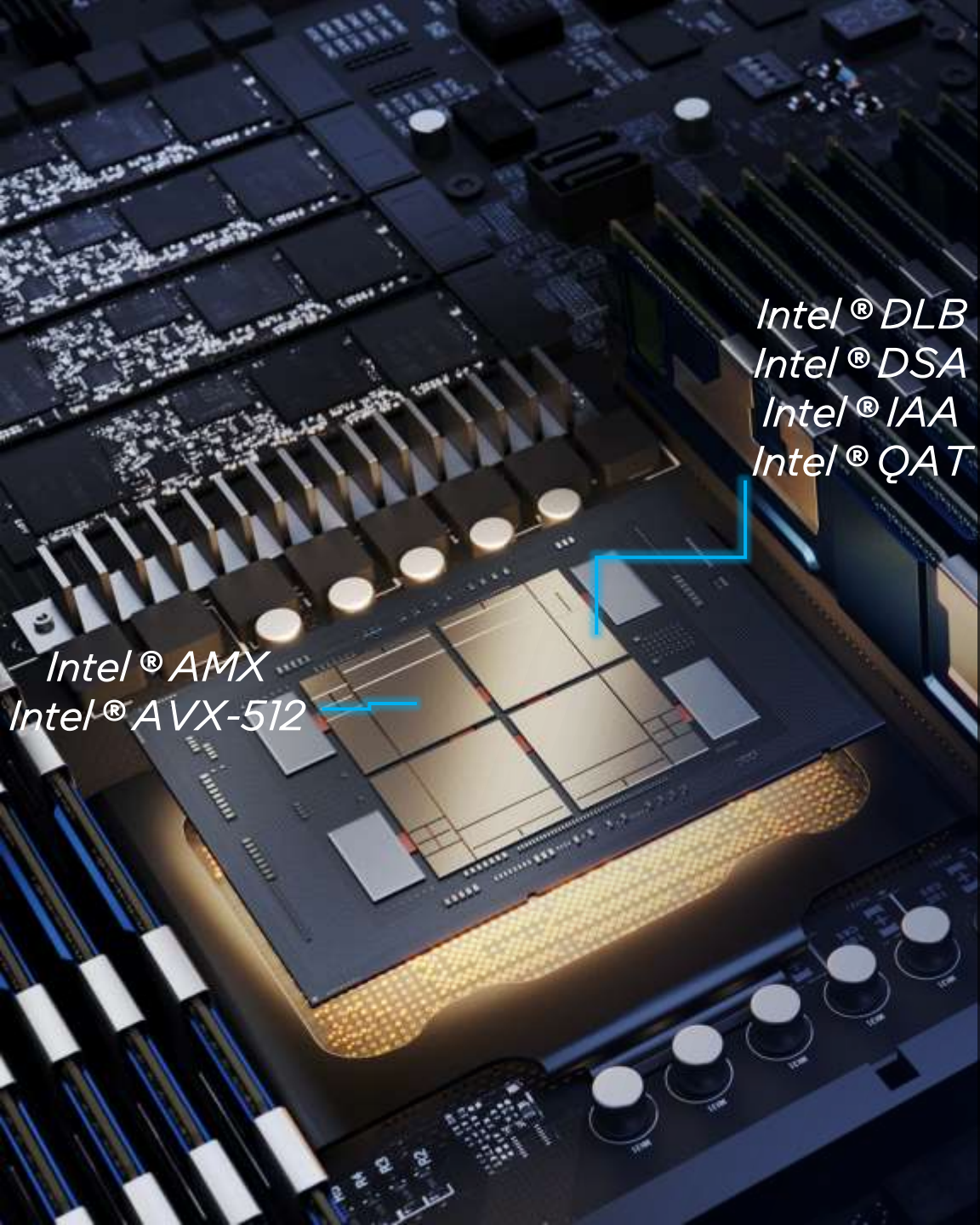


Spatial



Hybrid Compute Cluster in a Package





Intel® Xeon® CPU Max Series codenamed

*Intel® DLB
Intel® DSA
Intel® IAA
Intel® QAT*

Sapphire Rapids

HBM

*Intel® AMX
Intel® AVX-512*

AMX
Advanced Matrix Extensions

Integrated Acceleration Engines

64GB
HBM2e



Falcon Shores

GPU

Next Gen GPU
for AI & HPC

Converged Habana & Xe IP

Modular Tile-Based Architecture

HBM 3 & I/O designed to scale

Standard Ethernet Switching

Flexible CPU-GPU ratio

A single GPU programming Interface

CXL Programming Model

UCle

Universal Chiplet Interconnect Express

Reduced
Time-to-
Market

Reduced
IP Porting
Costs

Smaller,
Higher
Yielding
Components

Optimal, per-
Component
Tech

Leaders in semiconductors, packaging, IP,
cloud service providers joining forces

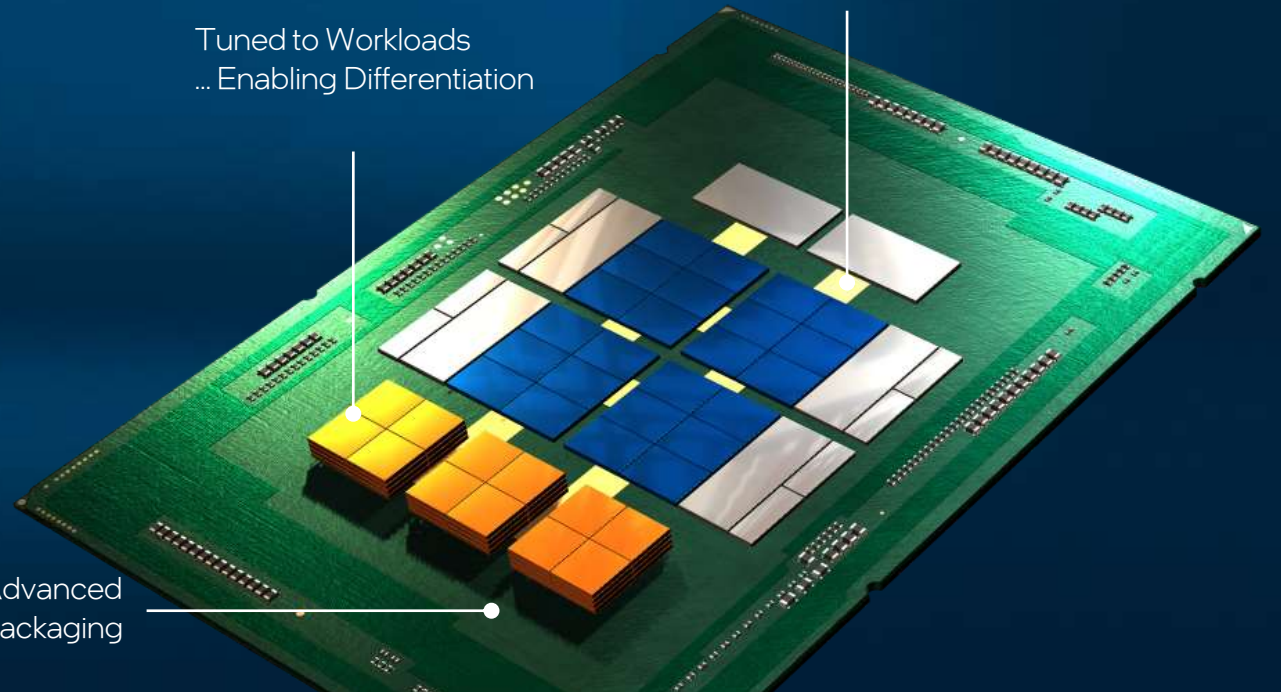
High-Speed Standardized
Chip-to-Chip Interface

Tuned to Workloads
... Enabling Differentiation

Advanced
Packaging



Google Cloud



Integrated Optical I/O

Key innovation for growing data rates, energy efficiency and channel loss minimization needs

2023 target

Bandwidth

~1 Tbps
per fiber

Reach

>100m

Shoreline
Density

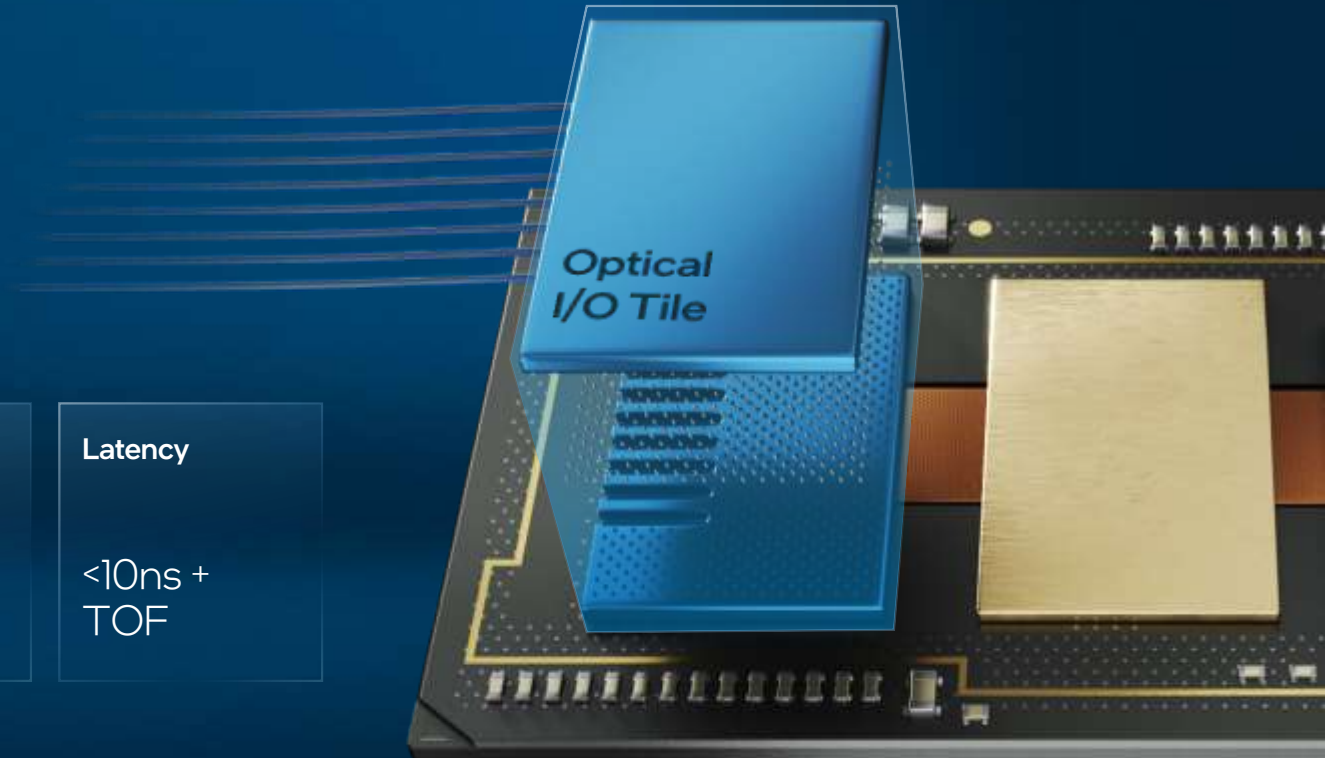
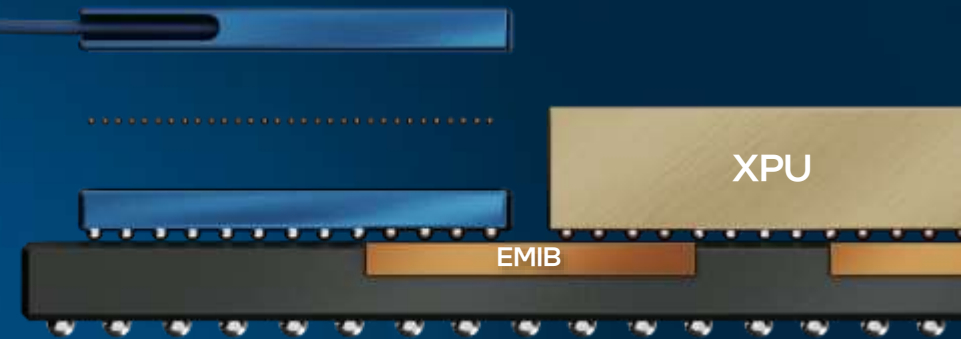
>4x
PCIe6

Energy
Efficiency

Trending
3pJ/b

Latency

<10ns +
TOF



Silicon

Systems

Software

The Open Standards—CXL™ is The Future

Solve these challenges with CXL

- Scaling challenges: **latency, bandwidth, capacity**
- Increase of heterogenous computing + massive datasets + demanding workloads = need for more accessible data, faster
- These computing demands require a more efficient interconnect **between CPU and traditional I/O interface**



Go Faster

- Improves data handling and reduces I/O bottlenecks



Do More

- Memory bandwidth and capacity expansion, efficient access across shared memory
- Enables CPU and accelerators to share memory resources for higher performance



Save More

- Improves TCO

Sources: [Introduction to Compute Express Link White Paper](#), March 2019 and <https://www.computeexpresslink.org/>

CXL™ Consortium – Scope and Feature

Coherent Interface

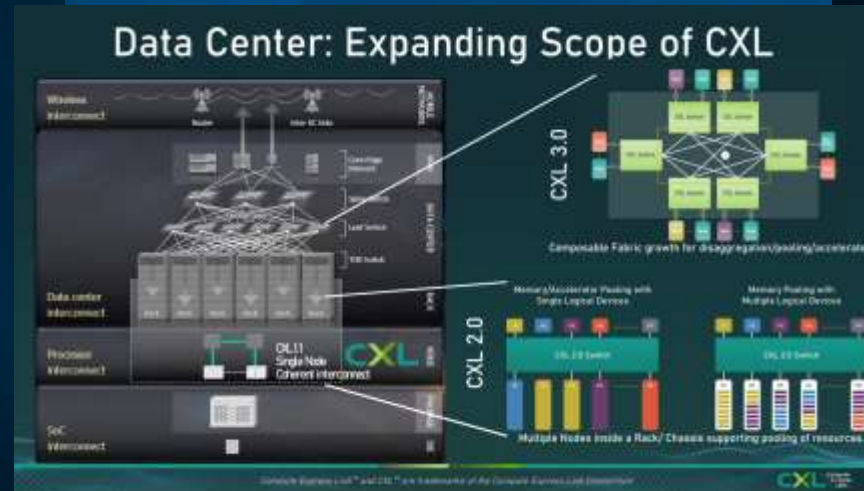
Leverage PCIe with three multiplexed protocols
Built on top of PCIe® infrastructure

Low Latency

CXL.Cache/CXL.Memory targets near CPU cache coherent latency (<200ns load to use)

Asymmetric

Complexity
Eases burden of cache coherence interface designs for devices



Heterogeneity

Enable 3 type of devices based on 3 protocols:
memory, cache, IO

Modularity & disaggregation
Allocate and deallocate resources on demand,

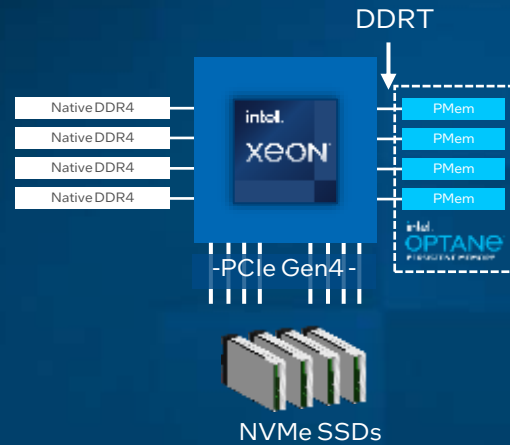
Enhance memory and cache coherency
Peer to peer memory access

Scalable

High speed low latency fabric
Composable fabric

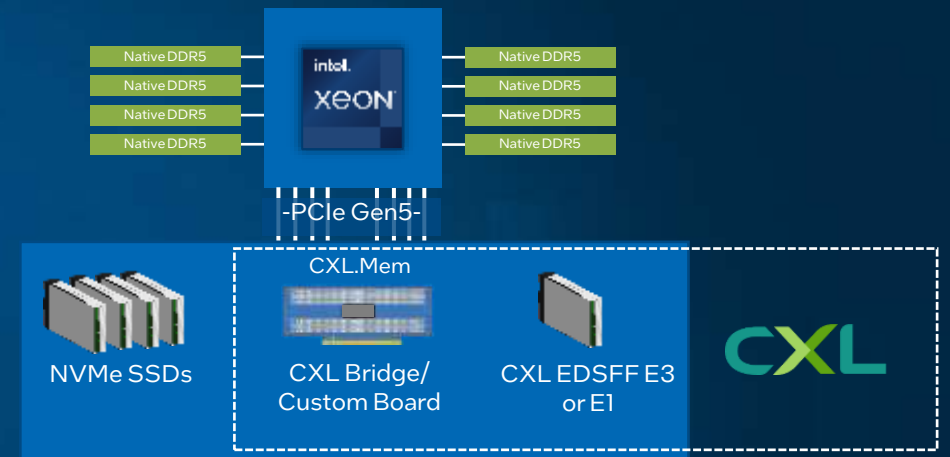
enable efficient resources sharing and modularity

Possible Usage Model Transition Examples



Today: Intel® Optane™ Technology

Intel® Xeon® CPU + DDR4 +
Intel® Optane™ Technology on DDRT

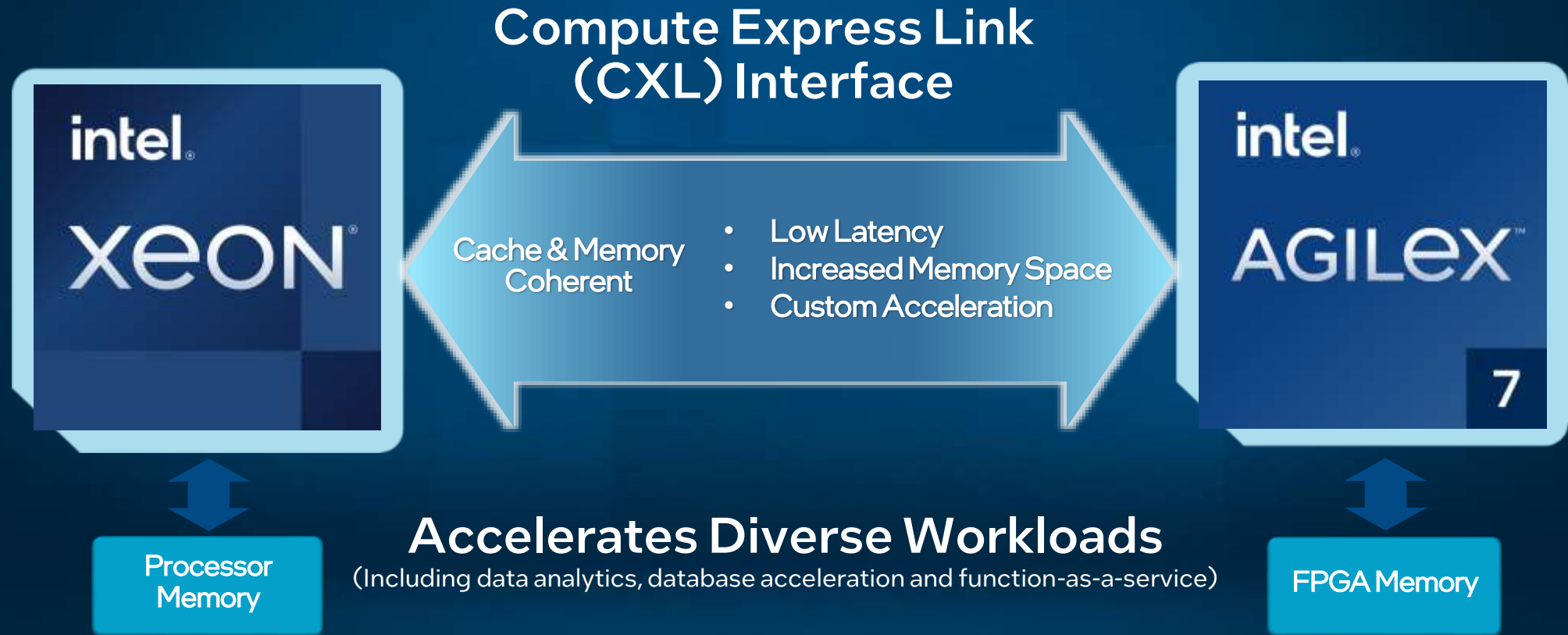


Future: CXL 2.0

Intel® Xeon® CPU + DDR5 +
Third-Party CXL Memory Products

Memory Mode	Cost-effective memory to meet workload needs and expanded memory capacity for workload scale-up.	Adds industry standard protocol for software to cache or tier memory.
Memory Expansion, Augmentation	Path for higher capacity than DRAM for workloads to scale-up.	Adds additional memory capacity and memory bandwidth to existing DDR attached DRAM.
Persistent Memory	Fast storage for meta data storage, fast write logs, and caching/tiering acceleration of other storage.	Adds persistence support (non-volatile memory over CXL).
High-Endurance, Performant SSDs	Very fast storage “replacement” for meta data storage, fast write logs, caching/tiering acceleration.	Adds persistence support (memory-semantic storage over CXL).

Coherent Discrete Accelerator for 4th Gen. Intel[®] Xeon[®] Scalable Processors



*Available on selected Intel Agilex 7 I-series and M-series FPGAs which contain at least one R-Tile.

<https://www.computeexpresslink.org/>

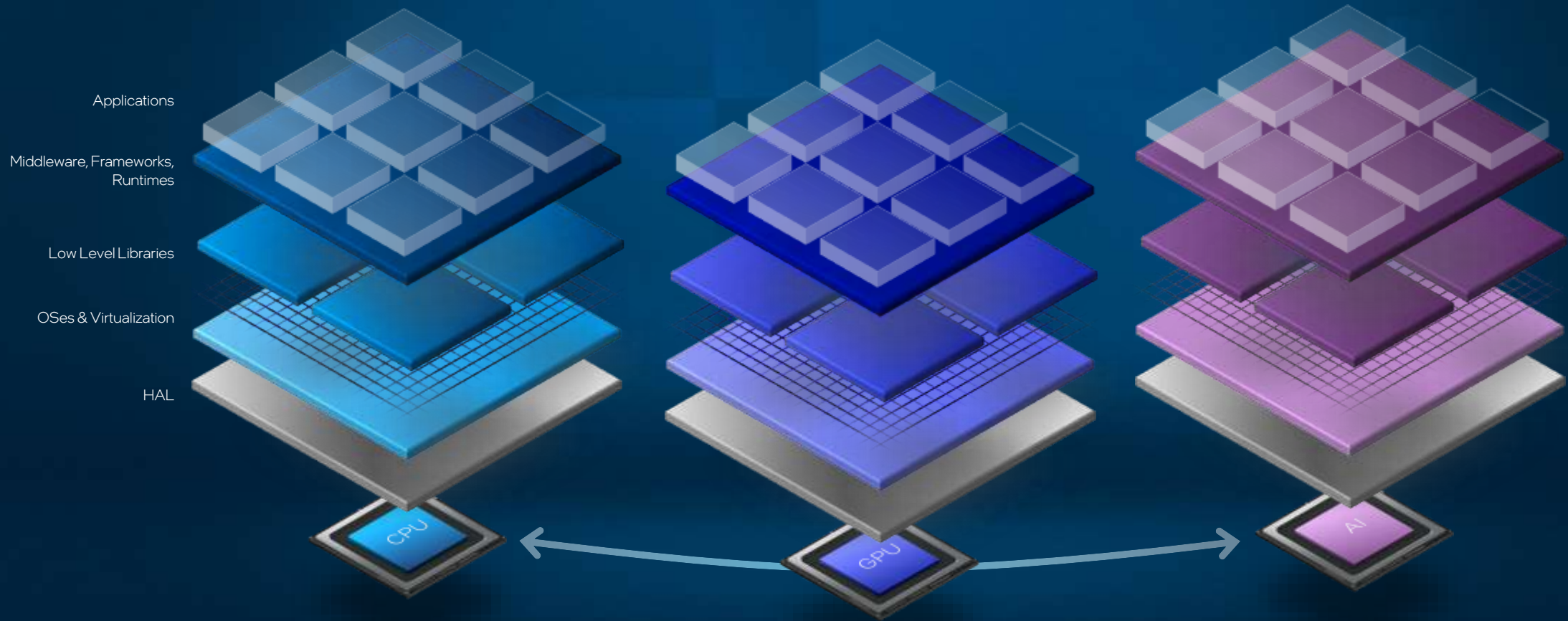


Silicon

Systems

Software

Unifying Software Stacks Critical...



Maximizing Impact, Minimizing “energy to solution” through...



Open

Ecosystem



Choice

Compatibility



Trust

Workloads



Scale

Delivery & Deployment



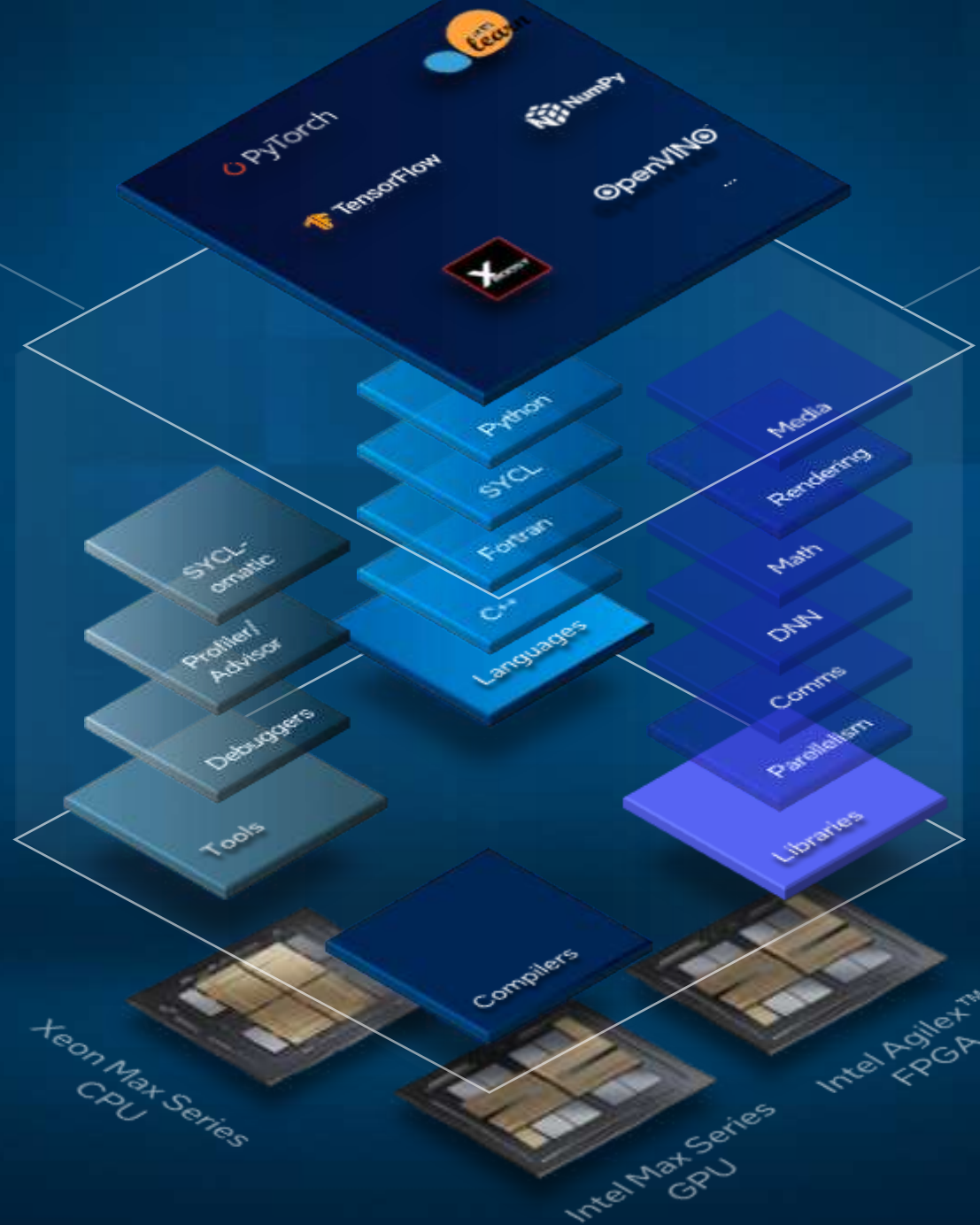
open, multiarchitecture,
multivendor programming

Open industry specification

Freedom in hardware choice

Performance, productivity
& portability

Standards-based, community-
driven



Intel's implementation
with a set of tools

Optimized for Intel hardware

Proven performance,
best-in-class capabilities

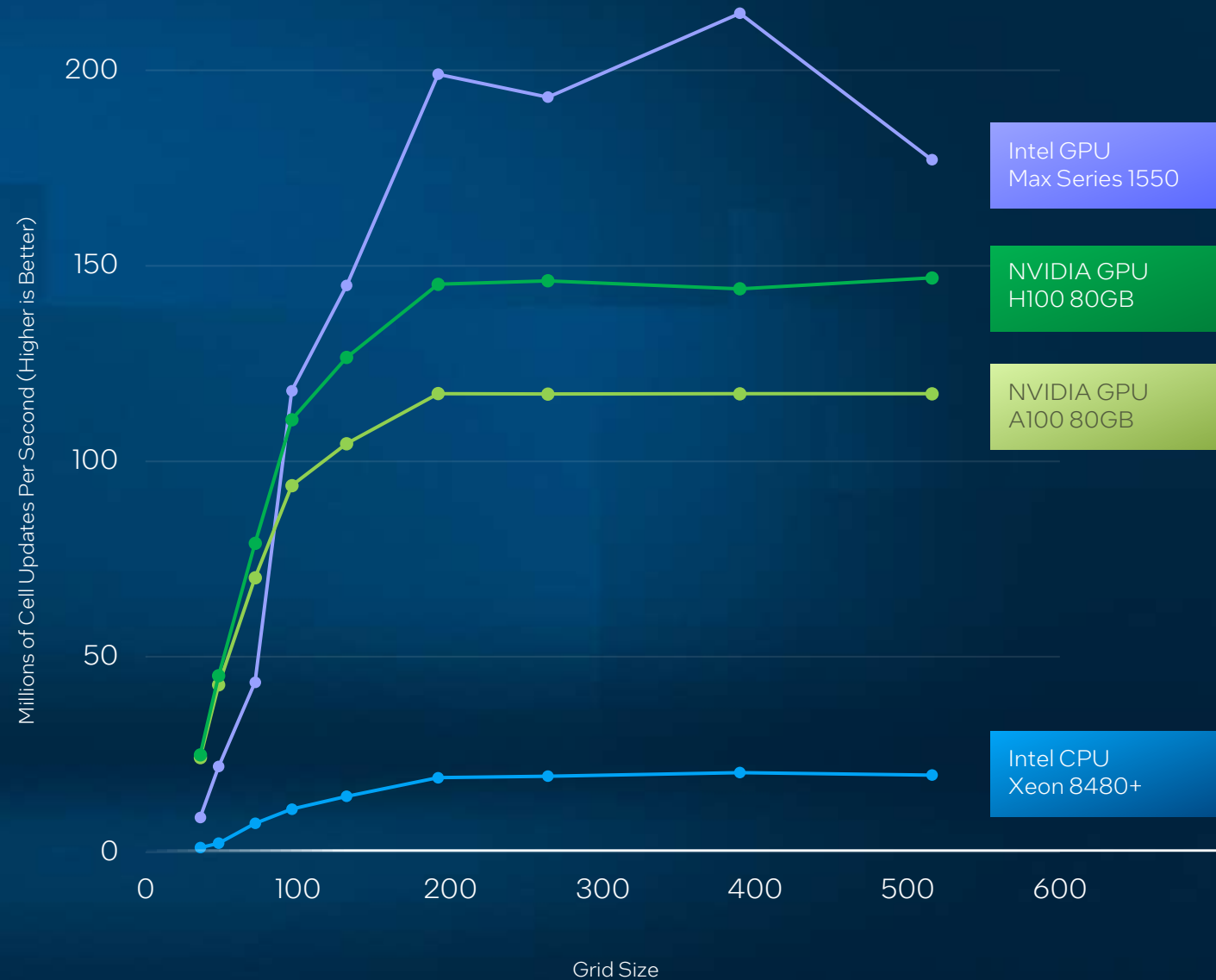
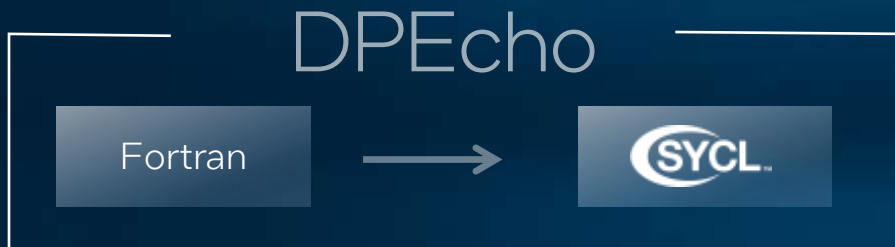
Supports SYCL, Fortran, Python,
OpenMP, MPI...

Enhanced CUDA-to-SYCL code
migration capabilities

Optimizations for TensorFlow &
PyTorch

Download free, commercial support
available

Write Once, Run Source Code Across Architectures & Across Vendors



See backup for workloads and configurations. Results may vary.

Drive innovation with Open Standards



The Intel logo is centered on a dark blue background. It features the word "intel" in a white, lowercase, sans-serif font. A small blue square is positioned above the letter "i". A registered trademark symbol (®) is located at the bottom right of the word.

intel®